CLAIMS

1. A circuit for a chip card module (3), comprising
   - a multilayer structure comprising an insulating substrate (4) having a first (5) and a second (6) sides, and a first conductive layer (7) supported by one of the first (5) and the second (6) sides of the insulating substrate (4);

   wherein said first conductive layer (7) is intended to be electrically connected to an electronic chip (12), with electrical wires (13) wire-bonded to the first conductive layer (7), wherein the first conductive layer (7) is a copper-based layer having a Vicker hardness greater than or equal to 100 VHN, and wherein the first conductive layer has a bonding surface onto which electrical wires (13) are intended to be connected with a roughness greater than or equal to 0.8 micrometres.

2. A circuit according to claim 1, comprising an electronic chip (12) and silver-based electrical wires (13) connected to both the electronic chip (12) and the first conductive layer (7), the silver-based electrical wires (13) being wire-bonded to the first conductive layer (7).

3. A circuit according to claim 2, wherein the silver-based electrical wires (13) are made a silver alloy.

4. A circuit according to claim 2 or 3, wherein the silver-based electrical wires (13) are made a silver alloy with an external gold layer.

5. A circuit according to any one of the preceding claims, wherein the multilayer structure comprises a copper-clad structure (18).

6. A circuit according to any one of the preceding claims, comprising
   - through-holes (15) punched in the insulating substrate (4) and the first conductive layer (7), and
   - a second conductive layer (8) laminated on a side (6) of the insulating substrate (4) opposite to the side of the insulating substrate (4) supporting the first conductive layer (7).

7. A circuit according to one of claims 5 to 6, comprising a second conductive layer (8) is supported by a side (6) of the insulating substrate (4) opposite to the side (5) of the insulating substrate (4) supporting the first conductive layer (7).

8. A circuit according to claim 7, wherein first conductive pads (9) are formed in the first conductive layer (7) and second conductive pads (10) are formed in the second conductive layer (8), silver-based electrical wires (13) being connected to both an electronic chip (12) and at least the first conductive pads (9), the silver-based electrical wires (13) being wire-bonded to the first conductive pads (9), and the second conductive pads (10) being adapted to establish a connection by electrical contact with a chip card reader.

9. A circuit according to any one of the preceding claims, wherein the first conductive layer (7) has a thickness ranging from 18 to 38 micrometres.